Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"4057659".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:33
L2		remove near metal near edge near laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:33
L3	24	remove near metal near laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:33
L4	6	3 and edge	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:45
L5	2348	219/121.69	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:46
L6	820	427/555	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:46
L8	284	427/556	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:46
L9	3102	5 or 6 or 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:46
L10	2846	9 and laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:47

L11	1840	10 and metal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:47
L12	48	11 and metal near remove	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:47
S1	2573	via near etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/10/11 09:29
S2	2296989	angle or angled	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:45
S3	335381	via and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:45
S4	3048512	via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:45
S5 .	3660	S2 near S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:46
S6	64	first near via near etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:46
S7	23	second near via near etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:47
S8	519107	taper or tapered	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:46

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S9	2016	S8 near S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:56
S11	231310	"193"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:50
S12	57	S9 and S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:53
S13	21	S12 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:21
S14	420	S9 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:59
S17	45	("4814041").URPN.	USPAT	OR	ON	2006/06/07 15:24
S18	1	"5354386".pn.	USPAT	OR	ON	2006/06/07 15:36
S19	49441	multi-layer	USPAT	OR	ON	2006/06/07 15:37
S20	834	tapered near via	USPAT	OR	ON	2006/06/07 15:42
S22	5	S19 same S20	USPAT	OR	ON	2006/06/07 15:37
S25	5	two near step near via near etch	USPAT	OR	ON	2006/06/07 15:47
S26	435	wine near glass	USPAT	OR	ON	2006/06/07 16:26
S27	130	S26 and via	USPAT	OR	ON	2006/06/07 15:47
S28	39	S27 and semiconductor	USPAT	OR	ON	2006/06/07 16:10
S29	16206	ARC and dielectric	USPAT	OR	ON	2006/06/07 16:10
S30	5	S28 and S29	USPAT	OR	ON	2006/06/07 16:21
S31	115	ARC near resist	USPAT	OR	ON	2006/06/07 16:21
S33	0	ARC near "193" near nm near resist	USPAT	OR	ON	2006/06/07 16:21
S34	158	"193" near nm near resist	USPAT	OR	ON	2006/06/07 16:21
S35	34	S34 and arc	USPAT	OR	ON	2006/06/07 16:22
S36	18	S35 and via	USPAT	OR	ON	2006/06/07 16:22
S37	5	wine near glass near via	USPAT	OR	ON	2006/06/07 16:28
S38	38	fluted near via	USPAT	OR	ON	2006/06/08 11:58

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S39	2	S38 and arc	USPAT	OR	ON	2006/06/07 16:28
S50	1	"6743712".pn.	USPAT	OR	ON	2006/06/07 16:37
S51	2195	SLAM	USPAT	OR	ON	2006/06/07 16:37
S52	263	SLAM and ARC	USPAT	OR	ON	2006/06/07 16:37
S53	26	S52 and taper	USPAT	OR	ON	2006/06/07 16:38
S54	5	S53 and semiconductor	USPAT	OR	ON	2006/06/07 16:38
S55	13	S52 and semiconductor	USPAT	OR	ON	2006/06/07 16:40
S56	2198	tapered near sidewall	USPAT	OR	ON	2006/06/07 17:01
S57	177	S56 and arc	USPAT	OR	ON	2006/06/07 16:55
S58	69	S57 and via	USPAT	OR	ON	2006/06/07 16:55
S59	29	S58 and semiconductor	USPAT	OR	ON	2006/06/07 16:56
S60	104	S56 and reflective	USPAT	OR	ON	2006/06/07 17:01
S61	25	S56 and antireflective	USPAT	OR ·	ON	2006/06/08 08:28
S62	1	"6368959".pn.	USPAT	OR	ON	2006/06/08 08:29
S63	1	"4814041".pn.	USPAT	OR	ON	2006/06/08 08:34
S64	103	silicon near arc	USPAT	OR	ON	2006/06/08 08:34
S65	206	organic near arc	USPAT	OR	ON	2006/06/08 08:34
S66	294	S64 or S65	USPAT	OR	ON	2006/06/08 08:34
S67	49073	international adj business	USPAT	OR	ON	2006/06/08 08:35
S68	45767	international adj business adj machines.as.	USPAT	OR	ON	2006/06/08 08:35
S69	15	S66 and S68	USPAT	OR	ON	2006/06/08 08:44
S70	2719	(taper or tapered) near sidewall	USPAT	OR	ON	2006/06/08 08:44
S71	11	tunable adj arc	USPAT	OR	ON	2006/06/08 08:44
S72	1	S70 and S65	USPAT	OR	ON	2006/06/08 08:46
S74	138	tapered adj via	USPAT	OR	ON	2006/06/08 08:53
S75	9195	PSG	USPAT	OR	ON	2006/06/08 08:53
S76	15715	TEOS	USPAT	OR	ON	2006/06/08 08:53
S77	222344	ARC	USPAT	OR	ON	2006/06/08 08:53
S78	252742	resist or photoresist or ("193" adj nm)	USPAT	OR	ON	2006/06/08 08:53
S79	155	S75 and S76 and S77 and S78	USPAT	OR	ON	2006/06/08 11:51
S80	1245177	"38" and "34"	USPAT	OR	ON	2006/06/08 11:59
S81	158	"193" near nm near resist	USPAT	OR	ON	2006/06/08 11:58
S82	38	fluted near via	USPAT	OR	ON	2006/06/08 11:58
S83	, 0	S82 and S81	USPAT	OR	ON	2006/06/08 11:58
S84	834	tapered near via	USPAT	OR	ON	2006/06/08 11:59
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S85	112	"193" near resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 11:59
S86	1528	tapered near via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:01
S87	331	sloped near via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:00
S88	1	angeled near via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:00
S91	2	"193" same S86	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:02
S92	2580	via near etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:02
S93	1	"193" same S92	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:36
S94	1528	tapered near via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:20
S95	1665254	semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:21
S96	345	S94 and S95	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:24

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S97	127	S96 and via.ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:24
S98 	1	"60437080"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:36
S99		"6874510".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 10:45
S10 0	1	10/829392	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:02
S10 1	2	"5875896".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 10:07
S10 2		"6683277".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 10:07
S10 3	52	resist adj spin adj coat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 10:45
S10 4	1	resist adj spin adj coat.ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 10:45